NTD40N03R

Power MOSFET
45 Amps, 25 Volts
N−Channel DPAK

Features

- Planar HD3e Process for Fast Switching Performance
- Low $R_{DS(on)}$ to Minimize Conduction Loss
- Low C_{iss} to Minimize Driver Loss
- Low Gate Charge
- Optimized for High Side Switching Requirements in High−Efficiency DC−DC Converters
- Pb−Free Packages are Available

MAXIMUM RATINGS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain−to−Source Voltage	V_{DSS}	25	Vdc
Gate−to−Source Voltage − Continuous	V_{GS}	±20	Vdc
Thermal Resistance − Junction−to−Case Total Power Dissipation @ T_C = 25°C Drain Current − Continuous @ T_C = 25°C, Chip − Continuous @ T_A = 25°C, Limited by Wires − Single Pulse (tp ≤ 10 μs)	$R_{\theta JC}$ P_D I_D I_D I_D	3.0 50 45 32 100	°C/W W A A A
Thermal Resistance − Junction−to−Ambient (Note 1) − Total Power Dissipation @ T_A = 25°C − Drain Current − Continuous @ T_A = 25°C	$R_{\theta JA}$ P_D I_D	71.4 2.1 9.2	°C/W W A
Thermal Resistance − Junction−to−Ambient (Note 2) − Total Power Dissipation @ T_A = 25°C − Drain Current − Continuous @ T_A = 25°C	$R_{\theta JA}$ P_D I_D	100 1.5 7.8	°C/W W A
Operating and Storage Temperature Range	T_J, T_{stg}	−55 to 175	°C
Maximum Lead Temperature for Soldering Purposes, 1/8 in from case for 10 seconds	T_L	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

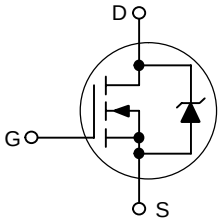
1. When surface mounted to an FR4 board using 0.5 sq. in pad size.
2. When surface mounted to an FR4 board using minimum recommended pad size.

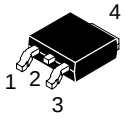
ON Semiconductor®

http://onsemi.com

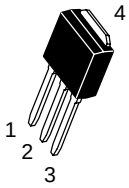
45 AMPERES, 25 VOLTS
$R_{DS(on)}$ = 12.6 mΩ (Typ)

N−CHANNEL



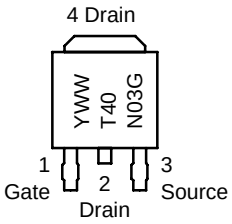


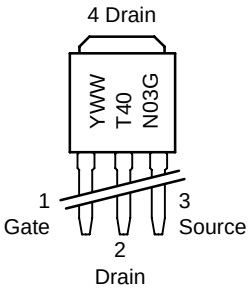
CASE 369AA
DPAK
(Surface Mount)
STYLE 2



CASE 369D
DPAK
(Straight Lead)
STYLE 2

MARKING DIAGRAM
& PIN ASSIGNMENTS





Y	= Year
WW	= Work Week
T40N03	= Device Code
G	= Pb−Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Characteristics	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain−to−Source Breakdown Voltage (Note 3) (V_{GS} = 0 Vdc, I_D = 250 μAdc) Temperature Coefficient (Positive)	$V(br)_{DSS}$	 25 –	 28 –	 – –	Vdc mV/°C
Zero Gate Voltage Drain Current (V_{DS} = 20 Vdc, V_{GS} = 0 Vdc) (V_{DS} = 20 Vdc, V_{GS} = 0 Vdc, T_J = 150°C)	I_{DSS}	 – –	 – –	 1.0 10	μAdc
Gate−Body Leakage Current (V_{GS} = ±20 Vdc, V_{DS} = 0 Vdc)	I_{GSS}	–	–	±100	nAdc
ON CHARACTERISTICS (Note 3)					
Gate Threshold Voltage (Note 3) (V_{DS} = V_{GS}, I_D = 250 μAdc) Threshold Temperature Coefficient (Negative)	$V_{GS(th)}$	 1.0 –	 1.7 –	 2.0 –	Vdc mV/°C
Static Drain−to−Source On−Resistance (Note 3) (V_{GS} = 4.5 Vdc, I_D = 10 Adc) (V_{GS} = 10 Vdc, I_D = 10 Adc)	$R_{DS(on)}$	 – –	 18.6 12.6	 23 16.5	mΩ
Forward Transconductance (Note 3) (V_{DS} = 10 Vdc, I_D = 10 Adc)	g_{FS}	–	20	–	Mhos
DYNAMIC CHARACTERISTICS					
Input Capacitance	(V_{DS} = 20 Vdc, V_{GS} = 0 V, f = 1 MHz)	C_{iss}	–	584	–	pF
Output Capacitance		C_{oss}	–	254	–	
Transfer Capacitance		C_{rss}	–	99	–	
SWITCHING CHARACTERISTICS (Note 4)					
Turn−On Delay Time	(V_{GS} = 10 Vdc, V_{DD} = 10 Vdc, I_D = 10 Adc, R_G = 3 Ω)	$t_{d(on)}$	–	4.5	–	ns
Rise Time		t_r	–	19.5	–	
Turn−Off Delay Time		$t_{d(off)}$	–	16.7	–	
Fall Time		t_f	–	3.5	–	
Gate Charge	(V_{GS} = 4.5 Vdc, I_D = 10 Adc, V_{DS} = 10 Vdc) (Note 3)	Q_T	–	5.78	–	nC
		Q_1	–	2.1	–	
		Q_2	–	2.5	–	
SOURCE−DRAIN DIODE CHARACTERISTICS					
Forward On−Voltage	(I_S = 10 Adc, V_{GS} = 0 Vdc) (Note 3) (I_S = 10 Adc, V_{GS} = 0 Vdc, T_J = 125°C)	V_{SD}	 – –	 0.85 0.71	 1.2 –	V_{dc}
Reverse Recovery Time	(I_S = 10 Adc, V_{GS} = 0 Vdc, dI_S/dt = 100 A/μs) (Note 3)	t_{rr}	–	20.4	–	ns
		t_a	–	8.25	–	
		t_b	–	12.1	–	
Reverse Recovery Stored Charge		Q_{RR}	–	0.007	–	μC

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
4. Switching characteristics are independent of operating junction temperatures.

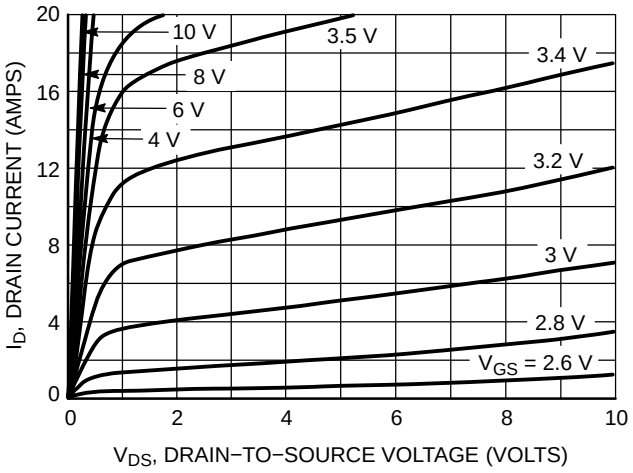


Figure 1. On−Region Characteristics

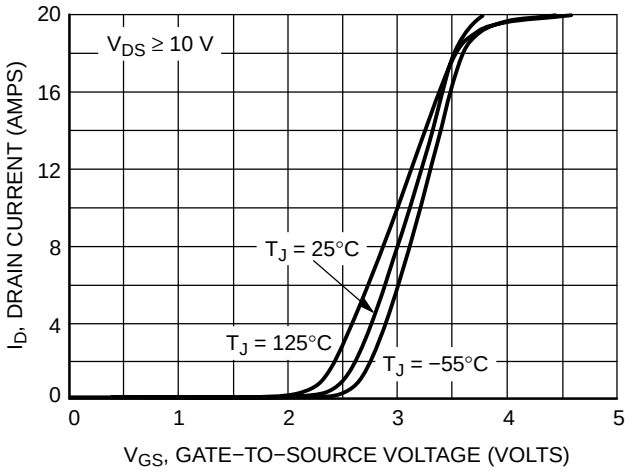


Figure 2. Transfer Characteristics

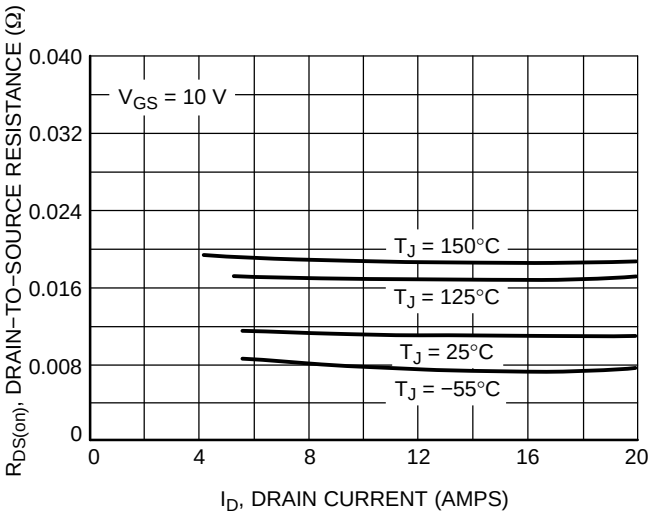


Figure 3. On−Resistance versus Drain Current and Temperature

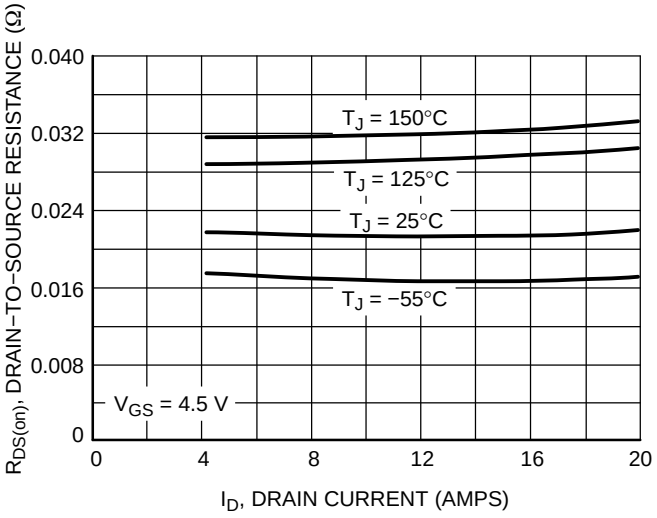


Figure 4. On−Resistance versus Drain Current and Temperature

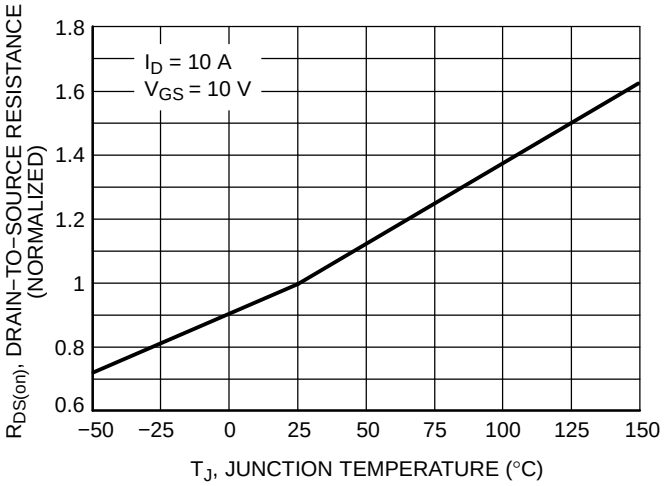


Figure 5. On−Resistance Variation with Temperature

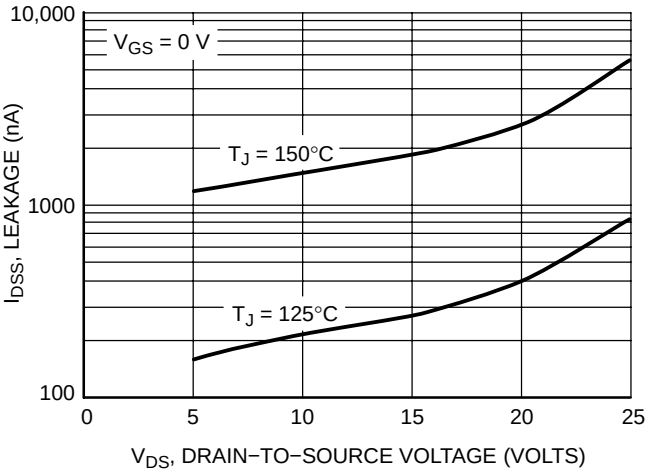


Figure 6. Drain−to−Source Leakage Current versus Voltage

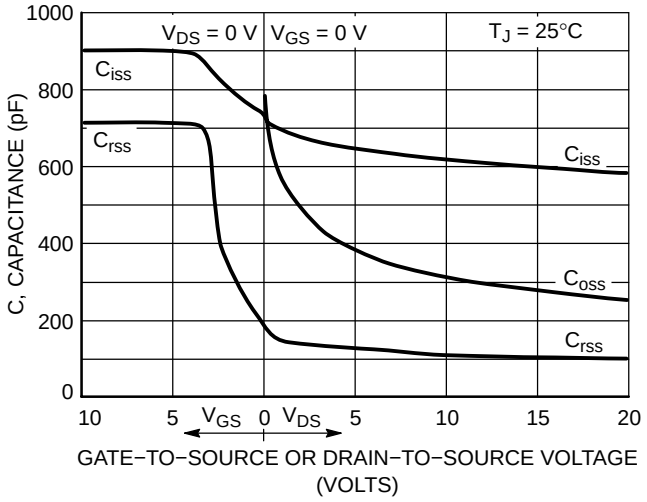


Figure 7. Capacitance Variation

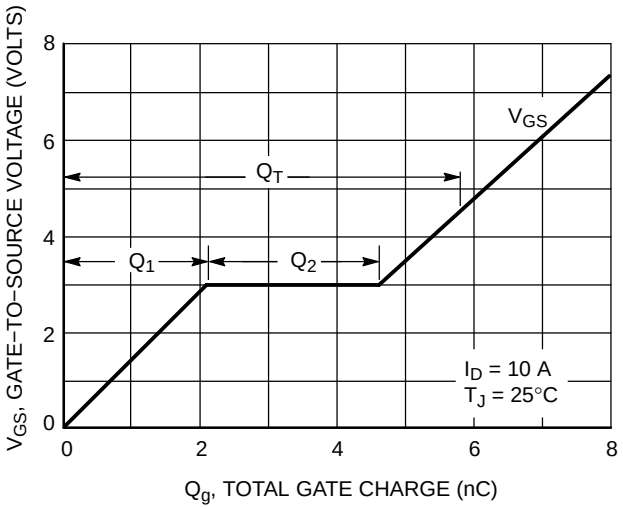


Figure 8. Gate−to−Source and Drain−to−Source Voltage versus Total Charge

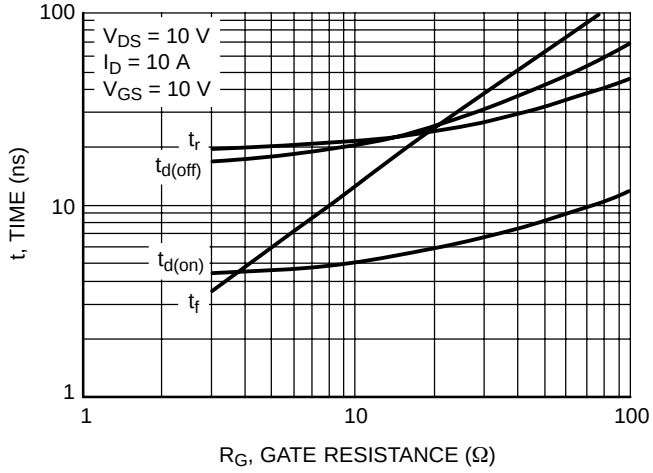


Figure 9. Resistive Switching Time Variation versus Gate Resistance

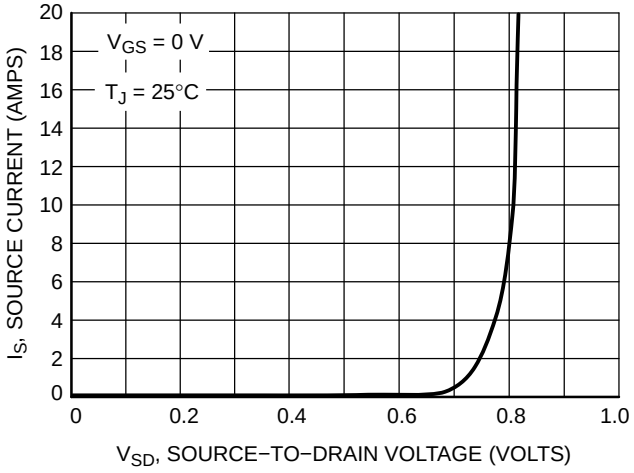


Figure 10. Diode Forward Voltage versus Current

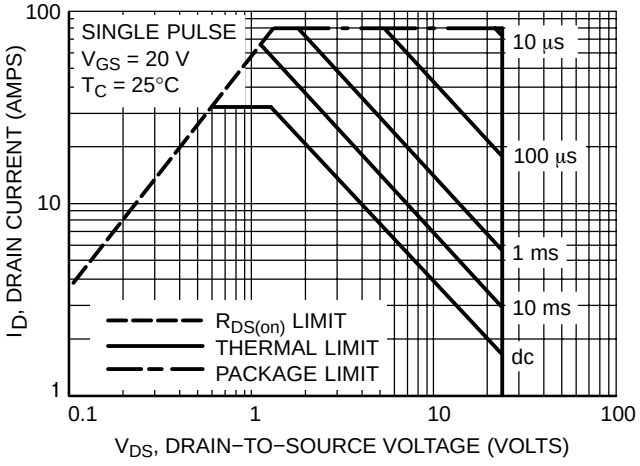


Figure 11. Maximum Rated Forward Biased Safe Operating Area

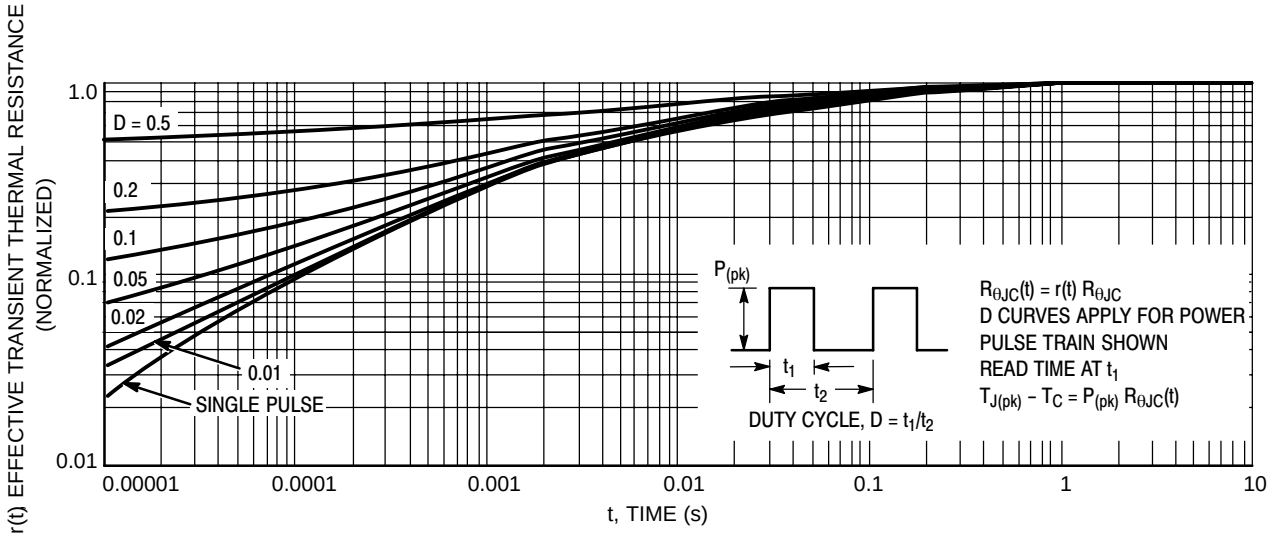


Figure 12. Thermal Response

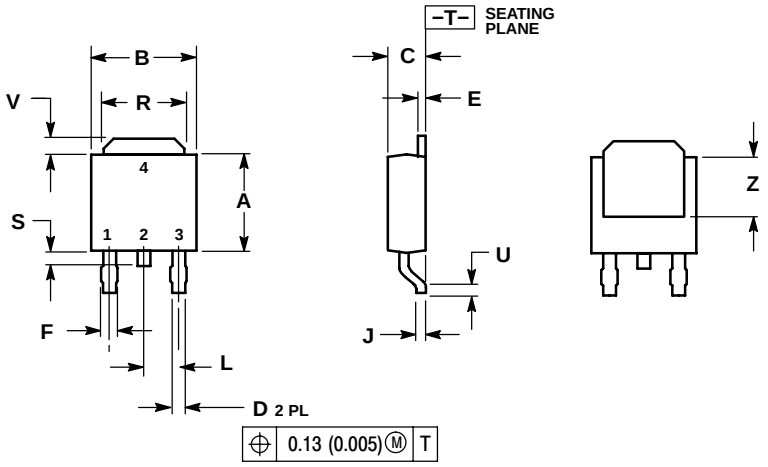
ORDERING INFORMATION

Device	Package	Shipping†
NTD40N03R	DPAK	75 Units/Rail
NTD40N03RG	DPAK (Pb−Free)	75 Units/Rail
NTD40N03R−1	DPAK (Straight Lead)	75 Units/Rail
NTD40N03R−1G	DPAK (Straight Lead) (Pb−Free)	75 Units/Rail
NTD40N03RT4	DPAK	2500 Tape & Reel
NTD40N03RT4G	DPAK (Pb−Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)
CASE 369AA−01
ISSUE O

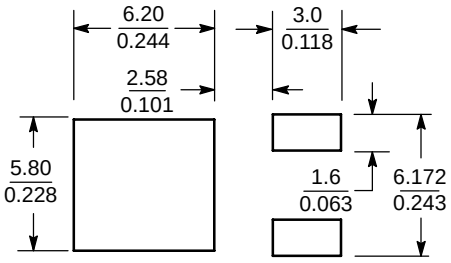


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.22
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.025	0.035	0.63	0.88
E	0.018	0.024	0.46	0.61
F	0.033	0.045	0.83	1.14
J	0.018	0.023	0.46	0.58
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020	−−−	0.51	−−−
V	0.035	0.050	0.89	1.27
Z	0.155	−−−	3.93	−−−

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

SOLDERING FOOTPRINT*

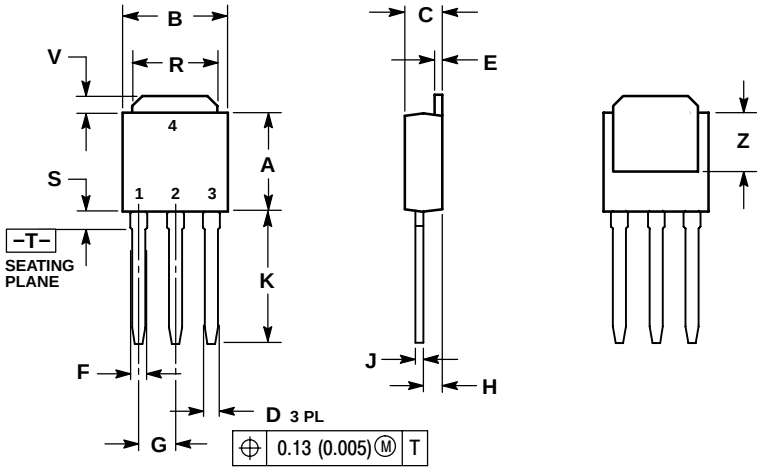


SCALE 3:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)
CASE 369D−01
ISSUE B



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	−−−	3.93	−−−

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 61312, Phoenix, Arizona 85082−1312 USA
Phone: 480−829−7710 or 800−344−3860 Toll Free USA/Canada
Fax: 480−829−7709 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center
2−9−1 Kamimeguro, Meguro−ku, Tokyo, Japan 153−0051
Phone: 81−3−5773−3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

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NTD40N03R/D